

Excerpt 2000's Copy

AN 127:184228 HCA
TI **Copper alloy** suitable for electric part showing high
adhesion with metal platings
IN Suzuki, Takeshi; Sakakibara, Tadao
PA Mitsubishi Shindo K. K., Japan
SO Jpn. Kokai Tokkyo Koho, 12 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN. CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 09209061	A2	19970812	JP 1996-18898	19960205
AB	The title Cu alloy contains Ni 0.5-3; Si 0.08-0.7; Sn 0.1-0.9; Zn 0.1-3; Fe 0.007-0.25; P 0.001-0.2; Mg 0.001-0.2; Pb 0.001-0.01; Li, In, Ba, Pd, Au, Pt, Rh, and/or Ir 0.0002-0.05 (as total); and optionally Cr 0.01-0.3 and/or Zr 0.01-0.3 wt.%. The alloy shows same tensile strength, elongation, elec. cond., as those of ordinary Cu alloys for elec. part.				

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